



SOT855-1

plastic thermal enhanced thin quad flat package; 64 leads;
body 10 x 10 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | Q (quad) |
| Package type descriptive code | HTQFP64 |
| Package type industry code | HTQFP64 |
| Package style descriptive code | HTQFP (thermal enhanced thin quad flat package) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MS-026 |
| Mounting method type | S (surface mount) |
| Issue date | 11-5-2005 |

Table 1. Package summary

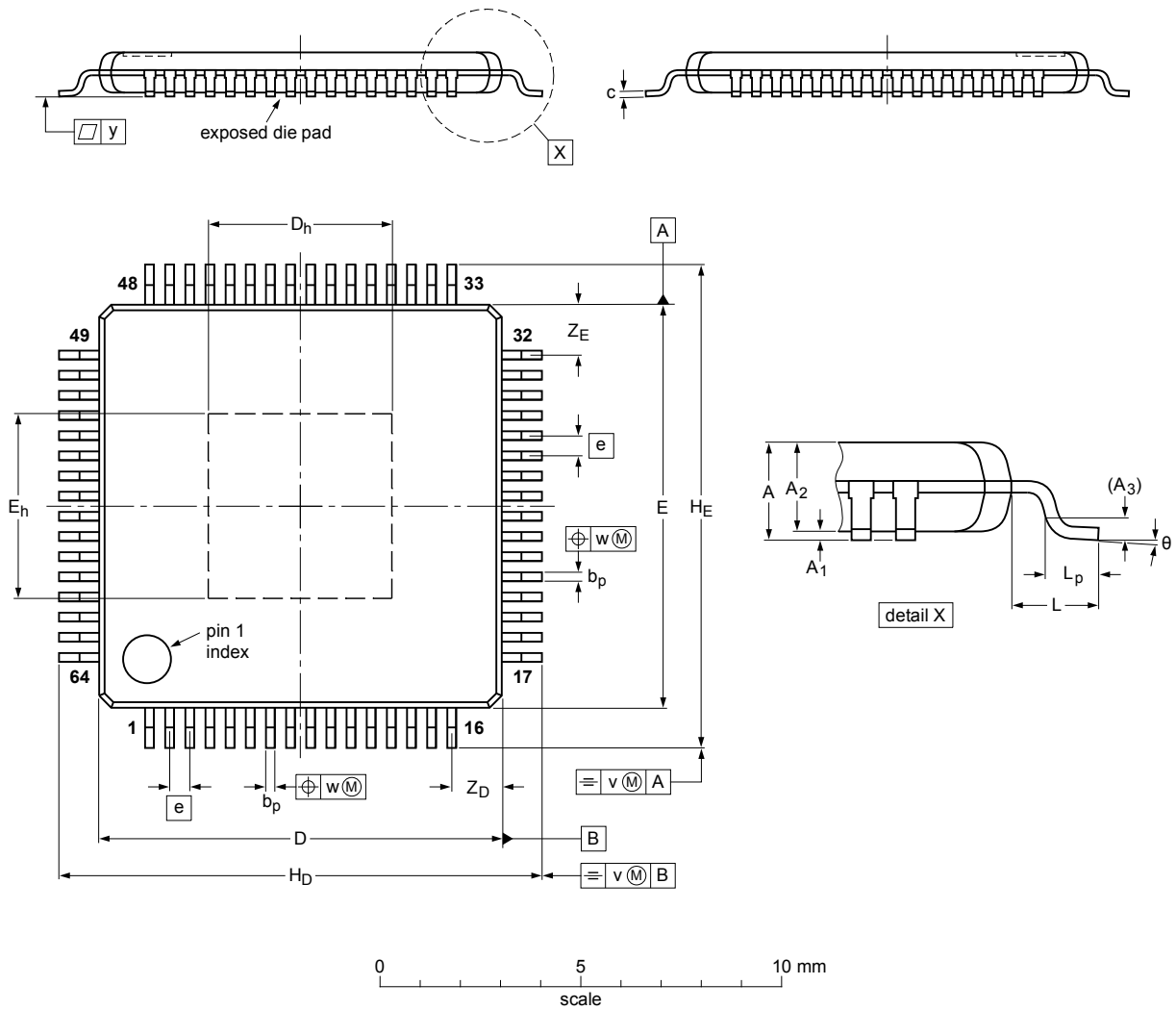
| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-------|------|------|
| D | package length | 9.9 | - | [tbd] | 10.1 | mm |
| E | package width | 9.9 | - | [tbd] | 10.1 | mm |
| A | seated height | [tbd] | - | [tbd] | 1.2 | mm |
| A ₂ | package height | 0.95 | - | [tbd] | 1.05 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 64 | - | |



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2. Package outline

HTQFP64: plastic thermal enhanced thin quad flat package; 64 leads; body 10 x 10 x 1 mm; exposed die pad SOT855-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A _{max} | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | H _D | H _E | L | L _p | v | w | y | Z _D ⁽¹⁾ | Z _E ⁽¹⁾ | θ |
|------|------------------|----------------|----------------|----------------|----------------|--------------|------------------|----------------|------------------|----------------|-----|----------------|----------------|---|----------------|-----|------|-----|-------------------------------|-------------------------------|---------|
| mm | 1.2 | 0.12 0.05 | 1.05 0.95 | 0.25 | 0.27 0.17 | 0.18 0.12 | 10.1 9.9 | 4.7 4.5 | 10.1 9.9 | 4.7 4.5 | 0.5 | 12.15 11.85 | 12.15 11.85 | 1 | 0.75 0.45 | 0.2 | 0.08 | 0.1 | 1.45 1.05 | 1.45 1.05 | 7° 0 |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|--------|-------|--|---------------------|-----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT855-1 | | MS-026 | | | | -04-05-18 05-05-11 |

Fig. 1. Package outline HTQFP64 (SOT855-1)

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3. Soldering

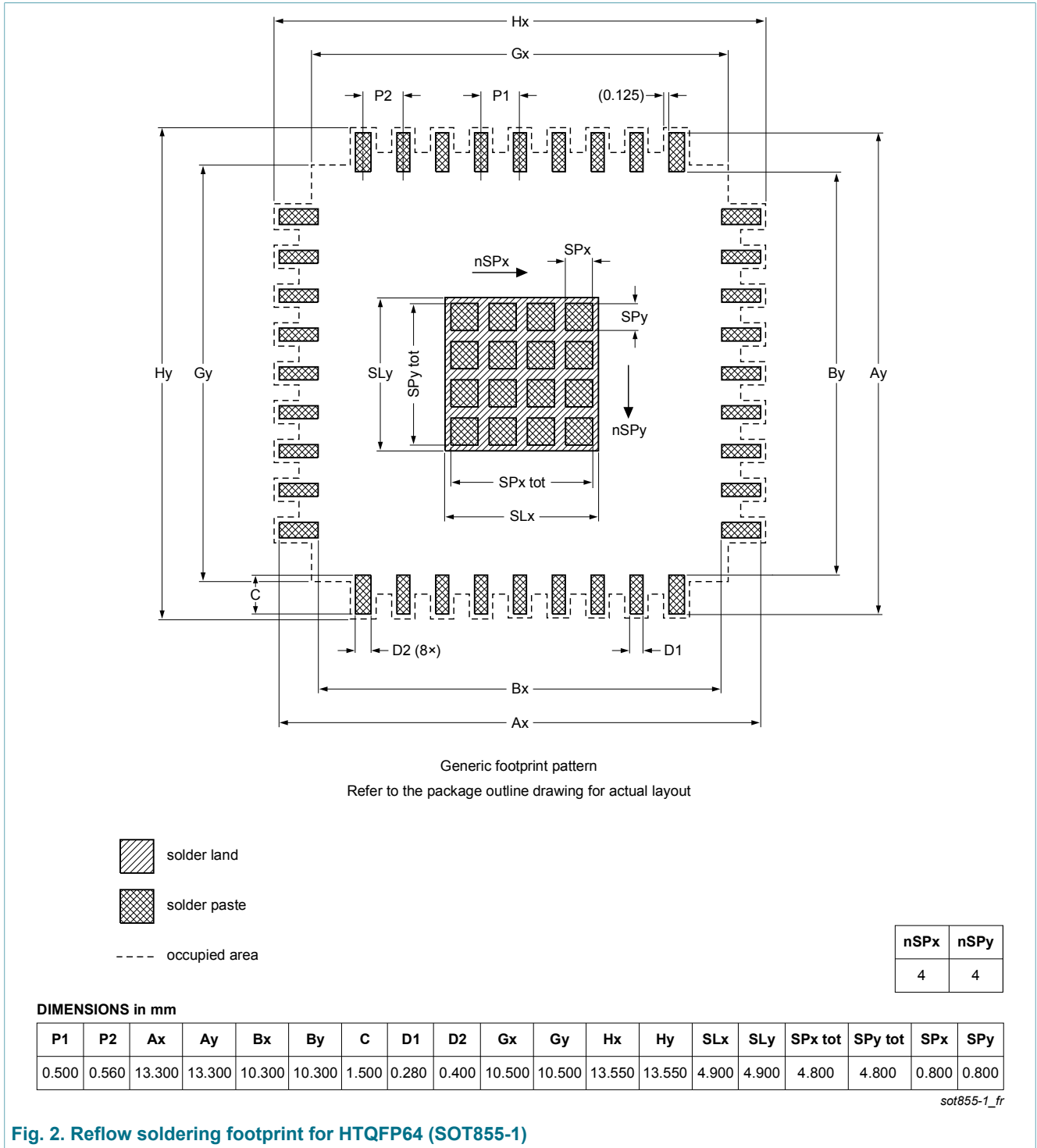


Fig. 2. Reflow soldering footprint for HTQFP64 (SOT855-1)

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4. Legal information

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